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Suzuki et al.

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- [54] **LIQUID CRYSTAL DISPLAY DEVICE AND METHOD OF PRODUCING THE SAME HAVING AN IMPROVED CONNECTION BETWEEN A FLEXIBLE FILM SUBSTRATE AND A DRIVE CIRCUIT SUBSTRATE**

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- [30] **Foreign Application Priority Data**

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- [51] Int. Cl.⁵ **G02F 1/1343; G02F 1/1333**

- [52] U.S. Cl. **359/88; 359/82**

- [58] Field of Search **359/82, 88**

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[57] **ABSTRACT**

A liquid crystal display device using a flexible film as a panel substrate is produced such that the panel substrate is connected to a drive circuit substrate detachable for reuse, that transparent electrodes on the panel substrate are free of damage from conductive particles in the connection, and that a hotmelt adhesive for connection may be prevented by a simple arrangement from being deteriorated with outside air. The liquid crystal display device employs the panel substrates of flexible film, in which transparent electrode terminals formed on the panel substrate are connected to wiring terminals formed on a drive circuit substrate. A radiation-setting adhesive such as an ultraviolet-curing adhesive and a photo-setting adhesive is coated on a surface of a connection portion forming the transparent electrode terminals of the panel substrate. Conductive members are projectively provided on a surface of a connection portion forming the wiring terminals of the drive circuit substrate. A hotmelt adhesive covers a surface of the drive circuit substrate including the conductive members.

14 Claims, 5 Drawing Sheets

